

ABSTRACT OF THE DISCLOSURE

A method of optimizing a bond out design includes steps of: (a) receiving as input an initial bond out design including at least one selected I/O pad and a top redistribution layer; (b) determining whether to include a lower redistribution layer in an optimized bond out design; (c) selecting a trace design to be included in the optimized bond out design for connecting the selected I/O pad to the top redistribution layer according to a bump function of the selected I/O pad; and (d) generating as output the optimized bond out design.